

**Express Mail Label No. EV317018750US**

**APPLICATION DATA SHEET  
UNDER 37 CFR §1.76**

**(1) Inventor Information**

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**(2) Assignee Information**

Name Line One:: Toppoly Optoelectronics Corp.  
Address Line One:: No. 12, Ke Jung Rd.  
Address Line Two:: Science-Based Industrial Park, Chu-Nan  
City:: Miao-Li County  
Country:: Taiwan, R.O.C.  
Postal or ZIP Code:: 350

**(3) Correspondence Information**

Customer No.:: 3624  
Name Line One:: C. Frederick Koenig III  
Name Line Two:: Volpe and Koenig, P.C.  
Telephone No.:: 215-568-6400

**(4) Application Information**

Title Line One:: PROCESS FOR FORMING POLYCRYSTALLINE  
Title Line Two:: SILICON LAYER BY LASER CRYSTALLIZATION  
Total Drawing Sheets:: 10  
Drawing Type:: Formal  
Application Type:: Utility  
Docket No.:: TET-PT049

(5) Representative Information

Representative Customer No.: 3624

(6) Foreign Priority Information

Foreign Application One:: 092118424  
Filing Date:: July 4, 2003  
Country:: Taiwan, R.O.C.  
Priority Claimed:: YES